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What is claimed is:

1. Achemically amplifying type positive resist composition comprising a resin which has an alkali-soluble group protected by 2-alkyl-2-adamantyl group or 1-adamantyl-1-alkylalkyl group, and which, per se, is insoluble or slightly soluble in alkali but becomes soluble in alkali by the action of an acid; and a sulfonium salt acid generating agent represented by the following formula (I):

$$Q^{1}$$
 Q^{1}
 Q^{1}
 Q^{2}
 Q^{2}
 Q^{3}
 Q^{4}
 Q^{4}
 Q^{4}
 Q^{4}

wherein Q^1 , Q^2 and Q^3 independently represent hydrogen, hydroxyl, alkyl having 1 to 6 carbon atoms or alkoxy having 1 to 6 carbon atoms; and Q^4 represents perfluoroalkyl which may have a cyclic structure.

- 2. The positive resist composition according to claim 1 which contains the resin in an amount of 80 to 99.9 % by weight, and the acid generating agent, including the sulfonium salt acid generating agent represented by the following formula (I) and another acid generating agent, in an amount of 0.1 to 20 % by weight based on the total solid component weight of the resist composition.
 - 3. The positive resist composition according to claim 1

wherein the perfluoroalkylsulfonate anion represented by $Q^4SO_3^-$ in the formula (I) has 4 or more carbon atoms.

4. The positive resist composition according to claim 1 wherein the resin has at least one polymerization unit selected from those represented by the following formula (IIa), (IIb), (IIc) or (IId):

wherein R_1 and R_3 represent hydrogen or methyl; and R_2 , R_4 and R_5 represent alkyl.

- 5. The positive resist composition according to claim 1 wherein the resin contains a polymerization unit having a group cleavable by the action of an acid within a range of 30 to 80% by mole.
- 6. The positive resist composition according to claim 1
 15 wherein 20% by mole or more of the polymerization unit of the resin is represented by the formulae IIa, IIb, IIc or Iid.